

BASIC BLADE & BEAM HEADER & SOCKET

(0.80 mm) .0315" PITCH • BTE/BSE SERIES



BTE
Mates:
BSE

BSE
Mates:
BTE

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating:
2 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC with 5 mm Stack Height
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (020-080)
(0.15 mm) .006" max (100-120)*
*(.004" stencil solution may be available; contact IPG@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold
Edge Mount Capability
Friction Lock option
11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)



Note:
Some lengths, styles and options are non-standard, non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,
-080, -100, -120

Specify LEAD STYLE from chart

-F
= Gold Flash on contact, Matte Tin on tail

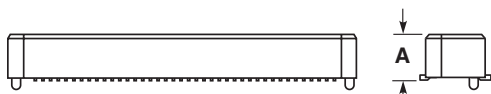
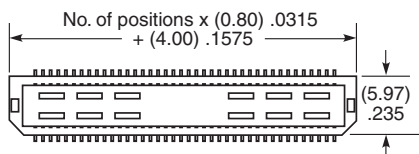
-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails (*-C Plating passes 10 year MFG testing)

-K
= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (80 positions maximum)

-FR
= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (80 positions maximum)



LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"
-02	(8.00 mm) .315"

*Processing conditions will affect mated height.

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,
-080, -100, -120

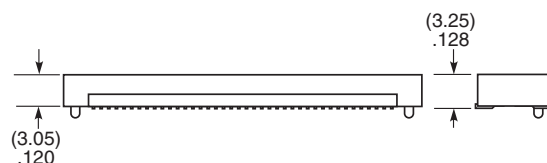
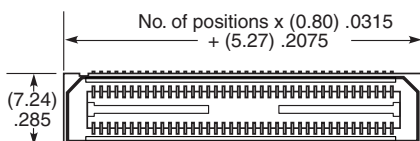
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